



THE OHIO STATE

UNIVERSITY

Inverse Design of Photonic Interconnects for Heterogeneous Integration

Student:	Bernard M. Melus			
Student Email: me		me	elus.1@osu.edu	
Faculty:	Prof. Ronald M. Reano			
Faculty Email: rea		rea	ano.1@osu.edu	
AFRL Sponsor:			Dr. Joseph S. Suelzer	
AFRL Directorate:		te:	AFRL/RYDI	



Motivation

- Applications in signal processing, navigation, and quantum information are turning from electronics to photonics for solutions
- Several challenges exist with photonic integrated circuit (PIC) design
 - Packaging
 - Component fabrication variations
 - Large component footprint: increases cost/size of PICs, low component density
- Photonic inverse design is a promising solution to these issues



Packaged Si-PIC [1] L. Carroll et al.,

Introduction and Proposed Solution

- Efficiently coupling light into photonic waveguides requires precision alignment and transverse optical mode matching
 - Classical approach: active alignment, lensed fibers, inverted taper structures
- Goal: Use inverse design to create an efficient spot size converter for fiber-to-chip or chip-to-chip coupling

Passive self alignment structure

J. L. Gonzalez. et al..

for Heterogeneous Integration" [2]

Submicrometer PSAS-to-PSAS

Self-Alignment Technology



Magnitude of the Complex Electric Field

Inverse Design

- Classical photonic components are designed using intuitive geometries
- Inverse design uses adjoint method optimization •
- Can be formulated for any passive, linear photonic component
- Finite-difference frequency-domain solver (FDFD)

inverse design

optimization

formulation

objective

Open-source Stanford Photonic Inverse Design framework (SPINS-b) [3]

$$\nabla \times \frac{1}{\mu} \nabla \times \mathbf{E} - \boldsymbol{\omega}^{2} \boldsymbol{\epsilon}(\boldsymbol{p}) \mathbf{E} = -\mathbf{i} \boldsymbol{\omega} \mathbf{J} \quad (1)$$
$$\mathbf{E} = \left(\nabla \times \frac{1}{\mu} \nabla \times - \left(\boldsymbol{\omega}^{2} \boldsymbol{\epsilon}(\boldsymbol{p}) \right) \right)^{-1} (-\mathbf{i} \boldsymbol{\omega} \mathbf{J}) \quad (2)$$
$$\max_{\mathbf{p}} \mathbf{f}_{obj}(\mathbf{E}(\boldsymbol{\epsilon}(\mathbf{p})))$$
$$\mathbf{subject to } \mathbf{p} \in \mathbf{S}$$



2D Inverse Design Cleaved SMF-28 Fiber-to-Chip Edge Coupler

- Optimization parameters:
 - 10.4 μ m Gaussian source, λ = 1.55 μ m wavelength, 11 x 25 μ m footprint
 - Objective function = overlap of field solution with the fundamental TE silicon nitride waveguide mode
 - Optimized on a CPU matrix solver with a 2D field solution
- Fabricated on the silicon nitride (SiN) American Institute for Manufacturing Integrated Photonics (AIM) passive multi-project wafer (MPW) process





2D Inverse Design Cleaved Fiber-to-Chip Edge Magnitude of Complex E field

- Lumerical finite-difference time-domain (FDTD) verification: 10.22 dB loss transmittance to the fundamental waveguide TE mode
- Experimental: 8.47 dB insertion loss
- High insertion loss as a result of using a 2D FDFD implementation, and failure to converge to a binary permittivity distribution
- Takeaways:
 - Proved that inverse design is a promising solution for designing efficient spot size converters
 Optimization solver needs to be in three spatial dimensions to
 - Optimization solver needs to be in three spatial dimensions to accurately model the problem
 - SEM imaging of the fabricated device helped determine fabrication and feature size constraints for future devices





3D Inverse Design of a Lensed Fiber-to-Chip Edge Coupler

- Biconjugate gradient GPU solver based on the NVIDIA CUDA architecture substantially reduced computation time allowing for 3D optimization
- Modeling the cleaved fiber problem in three dimensions requires a large simulation domain which is computationally demanding and accumulates numerical error due to ill-conditioned matrix
 - Optimization of a lensed fiber coupler reduced^{**} simulation domain size, 3.5 μm beam diameter vs. 10.4 μm cleaved fiber diameter
- As a baseline, coupling from a lensed fiber directly to the fundamental SiN TE waveguide resulted in a 4.41 dB loss in Lumerical FDTD



3D Inverse Design Fiber-to-Chip Edge Coupler Preliminary Simulation Results Magnitude of Complex E field

- The FDTD field solution at the focal point of a lensed SMF-28 fiber was used as the source initial condition in the FDFD solver
- The computational graph was formulated in a similar manner to the 2D problem, several alterations were made to optimize for different objectives:
 - No fabrication constraints, 4 x 10 μm footprint, 2.77 dB loss
 - Minimum feature size constraint, 4 x 12 μm footprint, 5.37 dB loss
 - Minimum feature size constraint, wideband optimization between 1.5 and 1.6 μ m, 4 x 14 μ m footprint, 4.53 dB loss at λ = 1.55 μ m



10.4 8.32 6.24 4.16 2.08 x(m) (x10^-6)

Graphic Design System (GDS) file and FDTD field solution

Summary and Direction

- The coupler designs were laid out for fabrication on an AIM SiN MPW run along with several other inverse design components and coupling experiments
- A GPU-based FDTD solver is being implemented that would expand the possibilities for rapid inverse design [4]
 - Exploit the inherent bandwidth property of time-domain solutions
 - Larger computational domain without the error in FDFD
- In addition to couplers, inverse design of coupled mode resonator components [5] and optical pulse shaping using nonlinear materials [6] is being explored



August AIM tapeout layout



Permittivity and instantaneous time-domain electric field solution of a waveguide simulated with fdtd-z

References

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- [6] Joshua Baxter and Lora Ramunno, "Inverse design of optical pulse shapes for time-varying photonics," Opt. Express 31, 22671-22684 (2023)